

Reliability and Test Condition

Item	Performance	Test Condition
High Temperature Exposure		Temperature: $125 \pm 2^\circ\text{C}$ Duration : 500hrs Measured at room temperature after placing for 24 ± 4 hrs
Temperature Cycling	Appearance: Cracking , chipping and any other defects harmful to the characteristics should not be allowed. Inductance: Within $\pm 10\%$ of initial value or spec tolerance.	Step1 : $-40 \pm 2^\circ\text{C}$ 30min Min. Step2 : Transition time 1min Max. Step3 : $125^\circ\text{C} \pm 2^\circ\text{C}$ 30min Min. Step4 : Transition time 1min Max. Number of cycles : 500 Measured at room temperature after placing for 24 ± 2 hrs
Biased Humidity		Humidity : $85 \pm 3\%$ R.H Temperature : $88.5^\circ\text{C} \pm 2^\circ\text{C}$ Duration : 500hrs Measured at room temperature after placing for 24 ± 2 hrs
Vibration	Appearance: Cracking , chipping and any other defects harmful to the characteristics should not be allowed.	Frequency range: 20HZ-80HZ, Maximum acceleration (m / s ²): 20G, Frequency sweep rate: 5HZ-80HZ, 2 cycles for each of X, Y, and Z axes for a total of 12 hours, No-load amplitude range: 1.52mm
Drop Test		0.45 ~ 9.54kg / 100cm height drop, test one corner, three sides, six sides

Item	Performance	Test Condition
<p>Solderability</p>	<p>Appearance: Cracking , chipping and any other defects harmful to the characteristics should not be allowed.</p> <p>More than 95% of the terminal electrode should be covered with solder. (Magnification 50X)</p>	<p>J-STD-002</p> <p>Steam Aging: 8 hours ± 15 min</p> <p>Preheat: 125°C, 60sec.</p> <p>Solder: Sn99.5%-Cu0. 5%</p> <p>Temperature: 245 ± 5°C</p> <p>Flux for lead free: Rosin. 9.5%</p> <p>Soldering time: 4 ± 1sec.</p>

